



Product/Process Change Notice - PCN 10_0241 Rev. B

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Conversion of LFCSP package outline from Punch to Sawn of package sizes 4x4, 5x5, 6x6 and 7x7mm and a transfer of assembly site.

Publication Date: 07-Mar-2012

Effectivity Date: 05-Jun-2012 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Add ADUC7020

Description Of Change

ADI has qualified and will be utilizing Assembly subcontractor STATS ChipPAC in Malaysia (SCM) for ADP5588, SSM2603, ADF4193, ADF7020 and ADUC7020 LFSCP products. ADI has qualified SCM's standard bill of materials in a SAWN singulated leadframe. See attached for BOM changes and package outline differences.

Rev. B

Note: The parts from Rev- will maintain original effectivity date of 21-Apr-2011. Added parts will have the standard 90 day effectivity.

Reason For Change

Sawn LFCSP is ADI's technology direction for LFCSP. The use of ADI qualified SCM as an assembly site will ensure continued source of product supply. ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability

The devices function and reliability as specified by the product datasheet will be unaffected by these changes. The Foot Print Dimension will remain the same for both punch and sawn LFCSP package

Product Identification *(this section will describe how to identify the changed material)*

Malaysia will be the country of origin (laser marked on the package) for parts assembled at STATS ChipPAC.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Reliability Report.

Supporting Documents

Attachment 1: Type: Package Outline Drawing

ADI_PCN_10_0241_Rev_B_Punch to Sawn rev.pdf

Attachment 2: Type: Qualification Report Summary

ADI_PCN_10_0241_Rev_B_Qualification Results.pdf

Attachment 3: Type: Detailed Change Description

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas:	PCN_Americas@analog.com	Europe:	PCN_Europe@analog.com	Japan:	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models

Existing Parts - Product Family / Model Number (22)

ADF4193 / ADF4193BCPZ	ADF4193 / ADF4193BCPZ-RL	ADF4193 / ADF4193BCPZ-RL7	ADF4193 / ADF4193SP1BCPZ	ADF4193 / ADF4193SP1BCPZ-RL
ADF4193 / ADF4193SP1BCPZ-RL7	ADF4193 / ADF4193SP2BCPZ-RL7	ADF4193 / ADF4193SP3BCPZ-RL7	ADF4193 / ADF4193WCCPZ-U1	ADF7020 / AD45203Z-RL
ADF7020 / AD57/002Z-0RL	ADF7020 / ADF7020BCPZ	ADF7020 / ADF7020BCPZ-RL	ADF7020 / ADF7020BCPZ-RL7	ADF7020-1 / ADF7020-1BCPZ
ADF7020-1 / ADF7020-1BCPZ-RL	ADF7020-1 / ADF7020-1BCPZ-RL7	ADP5588 / ADP5588ACPZ-R7	ADSP-BF537SSTD / ADSST-IP4010	SSM2603 / SSM2603CPZ-R2
SSM2603 / SSM2603CPZ-REEL	SSM2603 / SSM2603CPZ-REEL7			

Added Parts On This Revision - Product Family / Model Number (6)

ADUC7020 / ADUC7020BCPZ62	ADUC7020 / ADUC7020BCPZ62-RL7	ADUC7020 / ADUC7020BCPZ62I	ADUC7020 / ADUC7020BCPZ62I-RL	ADUC7020 / ADUC7020BCPZ62I-RL7
ADUC7020 / ADUC7020SRTZ				

Appendix B - Revision History

Rev	Publish Date	Rev Description
Rev. -	21-Jan-2011	Initial Release
Rev. A	19-Sep-2011	Removal of ADUC7020 not changing.
Rev. B	07-Mar-2012	Add ADUC7020

Analog Devices, Inc.

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